

SCANNING ACOUSTIC MICROSCOPE **VUE 400-P-NexGen**

Semiconductor Package Failure Analysis
 voids · disbonds · cracks · delamination
 · internal defects



Customer Interface

Dual 22" HD LED Monitors

Fixtures

Tray Fixture

Instrumentation

Digital Pulser Receiver
 Ultrasonic Digitizer (Max 12 GHz)

User Experience Elements

Dual JEDEC Trays
 HD LED Lighting
 Stainless Steel Tank

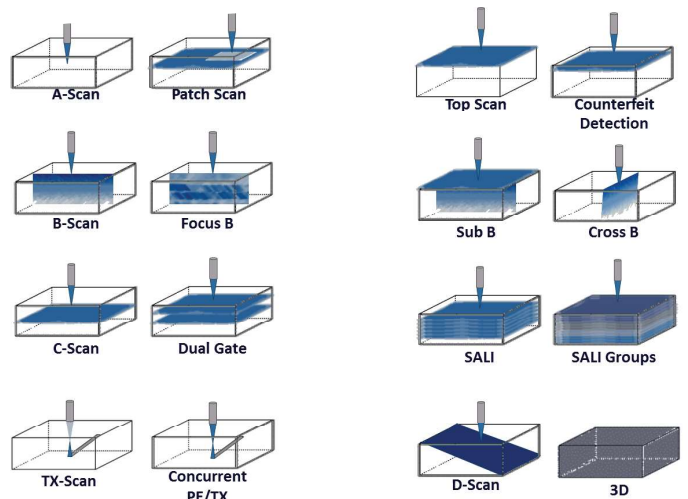
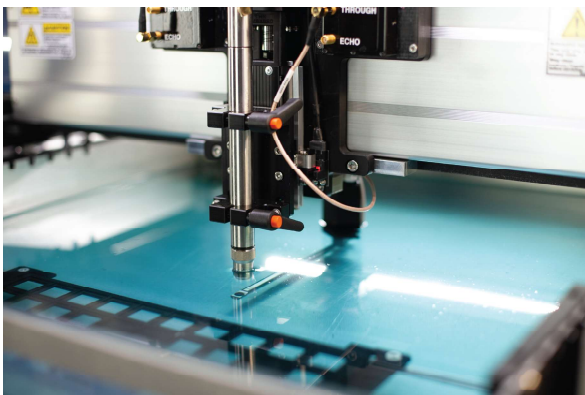
Maintenance Free Scan Axis

Motor:	Quad Linear Servo
Max Velocity:	1500 mm/s
Accuracy & Repeatability:	+/- 0.5 micron

Scan Length:	400 mm
Step Length:	380 mm
Focus Length:	35 mm

C-Scan Area:	360 mm x 350 mm
T-Scan Area:	360 mm x 220 mm

Weight: 250 Kg.

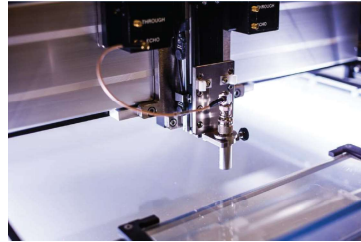


GET IN TOUCH

OKOS Digital Imaging System (ODIS)

Included Software Modes:

- Basic (user friendly)
- Advanced (detailed analysis)
- Production (automated scanning)
- Off-line Analysis (virtual scanning)



OKOS Digital Imaging System (ODIS)



VUE 250-P imaging power surpasses modern standards delivering premium FA Lab features to semiconductor fabrication facilities. ODIS is the latest Acoustic Microscopy software with rich technical content built on current platforms and industry feedback. Advanced analysis is provided through quantitative tools for measurement and classification of parts.

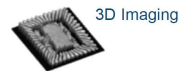
The Analysis version of ODIS allows non-scanning computers to virtually scan, view, and analyze data for simultaneous real-time analysis or post collection review.

- Counterfeit Detection
- Product Inspection
- Product Reliability
- Quality Control
- Process Validation
- Failure Analysis
- Vendor Qualification
- R&D

Application Specific Transducers

for the highest quality resolution.

Multiple transducer design for enhanced scan capability.



3D Imaging



C-scan with Multi-gate
SALI & SALI Groups



Advanced Time-of-Flight &
Thickness Measurements



Real-time A-scan &
A-scan Capture



Void Gating
(real-time)



Cluster Analysis
(post processing)



Threshold Mapping
(post processing)



B-scan & SLICE